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M. Brunson

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10/28/02

TECHNOLOGY CENTER 2800
AUG 22 2002



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:
Todd O. Bolken

Serial No.: 09/516,080

Filed: March 1, 2000

For: EXPOSED DIE MOLDING
APPARATUS

§
§ Group Art Unit: 2814
§
§
§ Examiner: Louie, W.
§
§
§
§ Atty Docket: MICS:0043 FLE/MAN
§ 99-0634

Assistant Commissioner
for Patents
Washington, D.C. 20231

CERTIFICATE OF MAILING 37 C.F.R. 1.8	
I hereby certify that this correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231, on the date below:	
August 5, 2002	<i>J. Presswood</i>
Date	Jennifer Presswood

Sir:

RESPONSE AND AMENDMENT

entered
10/28/02
amr

In response to the Final Official Action mailed on June 5, 2002, Applicant respectfully requests reconsideration of the above-identified application in view of the remarks and amendments set forth below.

IN THE CLAIMS

Please cancel claim 15 without prejudice.

Please amend claims 1 and 16 as set forth below:

1. (twice amended) A system for molding a circuit package comprising:

a first support plate;